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	Autore	Brown, Stuart
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""2012 IPFA Best Paper""; ""Laser Voltage Probing in Failure Analysis of Advanced Integrated Circuits on SOI""; ""Emerging Concepts and Techniques""; ""Closer to the Theoretical Limit: Spherical Corrections to Aplanatic Solid Immersion Imaging with Adaptive Optics""; ""Fault Isolation of Open Defects Using Space Domain Reflectometry""; ""Localization of Dead Open in a Solder Bump by Space Domain Reflectometry""
 ""Advanced Fault Isolation Technique Using Electro-Optical Terahertz Pulse Reflectometry (EOTPR) for 2D and 2.5D Flip-Chip Package""
 Novel Plasma FIB/SEM for High Speed Failure Analysis and Real Time Imaging of Large Volume Removal""; ""FemtoFarad/TeraOhm Endpoint Detection for Microsurgery of Integrated Circuit Devices""; ""Fault Isolation and Failure Analysis of TSV""; ""Cross Section Analysis of Cu Filled TSVs Based On High Throughput Plasma- FIB Milling""; ""Microstructural Considerations on the Reliability of 3D Packaging""
 ""High-Frequency TSV Failure Detection Method with Z Parameter""
 Enhanced Failure Analysis on Open TSV Interconnects""; ""Nanoprobeing Techniques""; ""A New Technique for Non-Invasive Short-Localisation in Thin Dielectric Layers by Electron Beam Absorbed Current (EBAC) Imaging""; ""Precise Localization of 28 nm via Chain Resistive Defect Using EBAC and Nanoprobeing""; ""In FAB 300 mm Wafer Level Atomic Force Probe Characterization""; ""Nanoelectronic Analog Circuit PFA a€? The Return of Circuit Level Probing""; ""Fault Isolation and Failure Analysis of 3D Packages""
 ""Enhanced Comparison of Lock-in Thermography and Magnetic Microscopy for 3D Defect Localization of System in Packages""
 Non Destructive Failure Analysis of 3D Electronic Packages Using Both Electro Optical Terahertz Pulse Reflectometry and 3D X-ray Computed Tomography""; ""Failure Analysis Using Scanning Acoustic Microscopy for Diagnostics of Electronic Devices and 3D System Integration Technologies""; ""Nanoprobeing Applications""; ""Analysis of an Anomalous Transistor Exhibiting Dual-Vt Characteristics and Its Cause in a 90 nm Node CMOS Technology""
 ""Study of Static Noise Margin, Cell Stability and Influence of Electron Beam on Sub-30 nm SRAM Using SEM-Based Nanoprobeing with 8 Nanoprobes""
 Leaky Device Channel Anomaly Identification and Case Study by Nano-Probing Technique, Curve Fitting, and Model Analysis""; ""Photon Based Techniques: An Understanding""; ""Photon Emission Spectra of FETs as Obtained by InGaAs Detector""; ""Near-Infrared Photon Emission Spectroscopy Trends in Scaled SOI Technologies""
 ""Characterization and TCAD Simulation of 90 nm Technology PMOS Transistor Under Continuous Photoelectric Laser Stimulation for Failure Analysis Improvement""
